

74AC20

Dual 4-Input NAND Gate

Features

- I_{CC} reduced by 50%
- Outputs source/sink 24mA


General Description

The AC20 contains four, 4-input NAND gates.

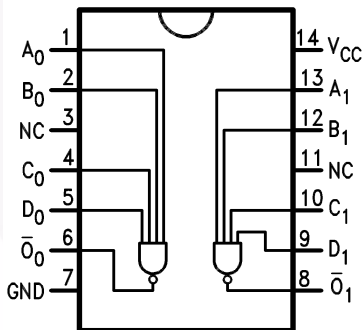
Ordering Information

Order Number	Package Number	Package Description
74AC20SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74AC20SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74AC20MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74AC20PC	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

 All packages are lead free per JEDEC: J-STD-020B standard.

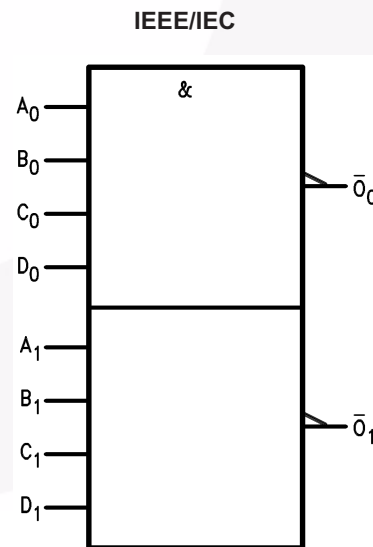
Connection Diagram



Pin Description

Pin Names	Description
A_n, B_n, C_n, D_n	Inputs
\bar{O}_n	Outputs

Logic Symbol



Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	-0.5V to +7.0V
I_{IK}	DC Input Diode Current $V_I = -0.5V$	-20mA
	$V_I = V_{CC} + 0.5$	+20mA
V_I	DC Input Voltage	-0.5V to $V_{CC} + 0.5V$
I_{OK}	DC Output Diode Current $V_O = -0.5V$	-20mA
	$V_O = V_{CC} + 0.5V$	+20mA
V_O	DC Output Voltage	-0.5V to $V_{CC} + 0.5V$
I_O	DC Output Source or Sink Current	$\pm 50mA$
I_{CC} or I_{GND}	DC V_{CC} or Ground Current per Output Pin	$\pm 50mA$
T_{STG}	Storage Temperature	-65°C to +150°C
T_J	Junction Temperature	140°C

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	2.0V to 6.0V
V_I	Input Voltage	0V to V_{CC}
V_O	Output Voltage	0V to V_{CC}
T_A	Operating Temperature	-40°C to +85°C
$\Delta V / \Delta t$	Minimum Input Edge Rate: V_{IN} from 30% to 70% of V_{CC} , V_{CC} @ 3.3V, 4.5V, 5.5V	125mV/ns

DC Electrical Characteristics

Symbol	Parameter	V _{CC} (V)	Conditions	T _A = +25°C		T _A = -40°C to +85°C		Units
				Typ.	Guaranteed Limits			
V _{IH}	Minimum HIGH Level Input Voltage	3.0	V _{OUT} = 0.1V or V _{CC} - 0.1V	1.5	2.1	2.1		V
		4.5		2.25	3.15			
		5.5		2.75	3.85			
V _{IL}	Maximum LOW Level Input Voltage	3.0	V _{OUT} = 0.1V or V _{CC} - 0.1V	1.5	0.9	0.9		V
		4.5		2.25	1.35			
		5.5		2.75	1.65			
V _{OH}	Minimum HIGH Level Output Voltage	3.0	I _{OUT} = -50μA	2.99	2.9	2.9		V
		4.5		4.49	4.4			
		5.5		5.49	5.4			
		3.0	V _{IN} = V _{IL} or V _{IH} , I _{OH} = -12mA		2.56	2.46		
		4.5			3.86	3.76		
		5.5			4.86	4.76		
V _{OL}	Maximum LOW Level Output Voltage	3.0	I _{OUT} = 50μA	0.002	0.1	0.1		V
		4.5		0.001	0.1			
		5.5		0.001	0.1			
		3.0	V _{IN} = V _{IL} or V _{IH} , I _{OL} = 12mA		0.36	0.44		
		4.5			0.36	0.44		
		5.5			0.36	0.44		
I _{IN} ⁽³⁾	Maximum Input Leakage Current	5.5	V _I = V _{CC} , GND		±0.1	±1.0		μA
I _{OLD}	Minimum Dynamic Output Current ⁽²⁾	5.5	V _{OLD} = 1.65V Max.			75		mA
I _{OHD}		5.5	V _{OHD} = 3.85V Min.			-75		mA
I _{CC} ⁽³⁾	Maximum Quiescent Supply Current	5.5	V _{IN} = V _{CC} or GND		2.0	20.0		μA

Notes:

1. All outputs loaded; thresholds on input associated with output under test.
2. Maximum test duration 2.0ms, one output loaded at a time.
3. I_{IN} and I_{CC} @ 3.0V are guaranteed to be less than or equal to the respective limit @ 5.5V V_{CC}.

AC Electrical Characteristics

Symbol	Parameter	V_{CC} (V) ⁽⁴⁾	$T_A = +25^\circ\text{C}$, $C_L = 50\text{pF}$			$T_A = -40^\circ\text{C to } +85^\circ\text{C}$, $C_L = 50\text{pF}$		Units
			Min.	Typ.	Max.	Min.	Max.	
t_{PLH}	Propagation Delay	3.3	2.0	6.0	8.5	1.5	10.0	ns
		5.0	1.5	5.0	7.0	1.0	8.0	
t_{PHL}	Propagation Delay	3.3	1.5	5.0	7.0	1.0	9.0	ns
		5.0	1.5	4.0	6.0	1.0	7.0	

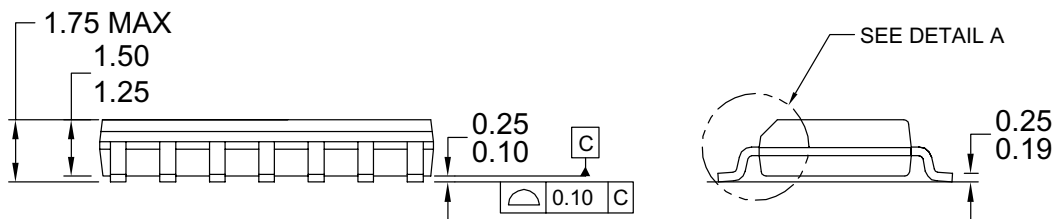
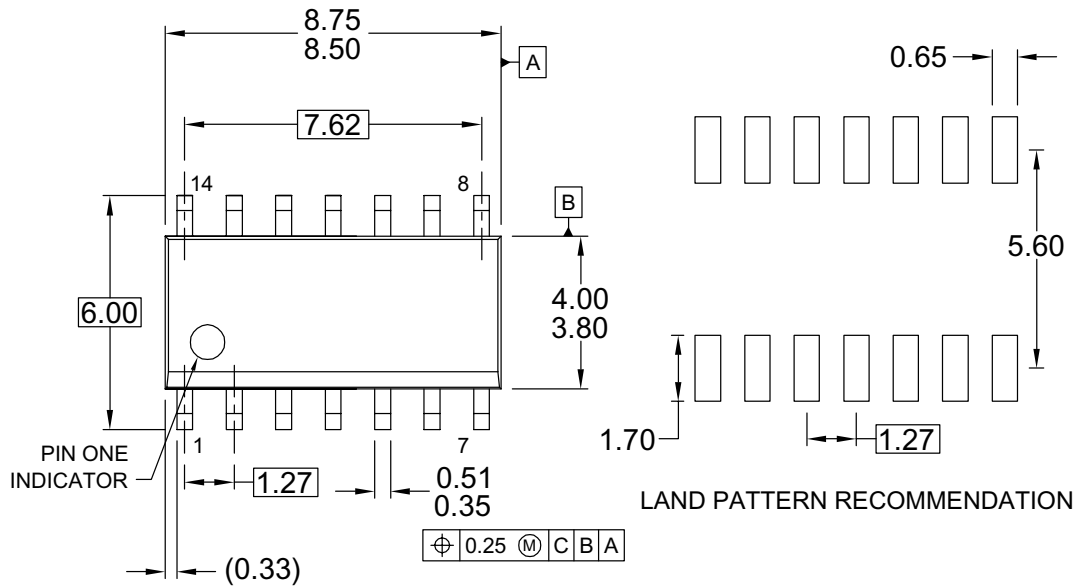
Note:

4. Voltage range 3.3 is $3.3\text{V} \pm 0.3\text{V}$. Voltage range 5.0 is $5.0\text{V} \pm 0.5\text{V}$.

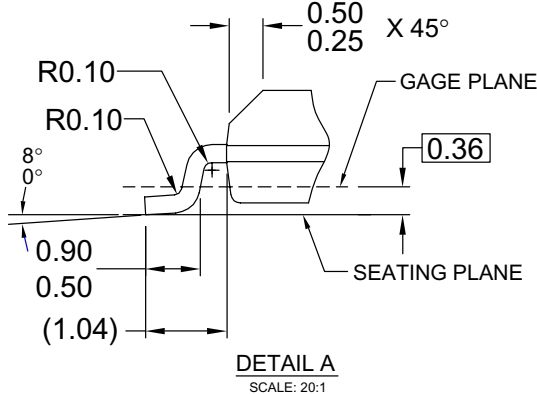
Capacitance

Symbol	Parameter	Conditions	Typ.	Units
C_{IN}	Input Capacitance	$V_{CC} = \text{OPEN}$	4.5	pF
C_{PD}	Power Dissipation Capacitance	$V_{CC} = 5.0\text{V}$	40.0	pF

Physical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED



- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X145-14M
- E) DRAWING CONFORMS TO ASME Y14.5M-1994
- F) DRAWING FILE NAME: M14AREV13

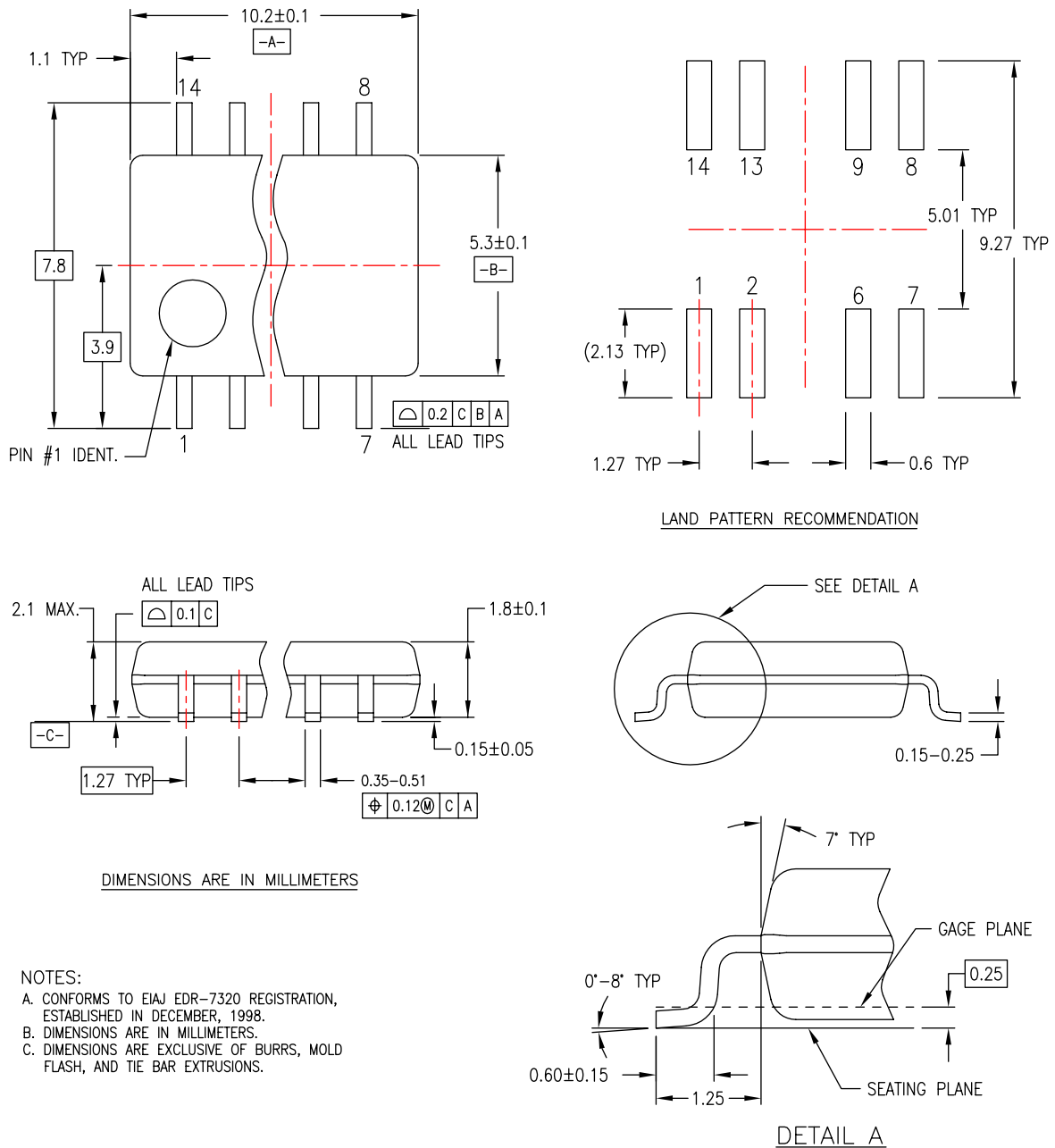
Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

<http://www.fairchildsemi.com/packaging/>

Physical Dimensions (Continued)



M14DREVC

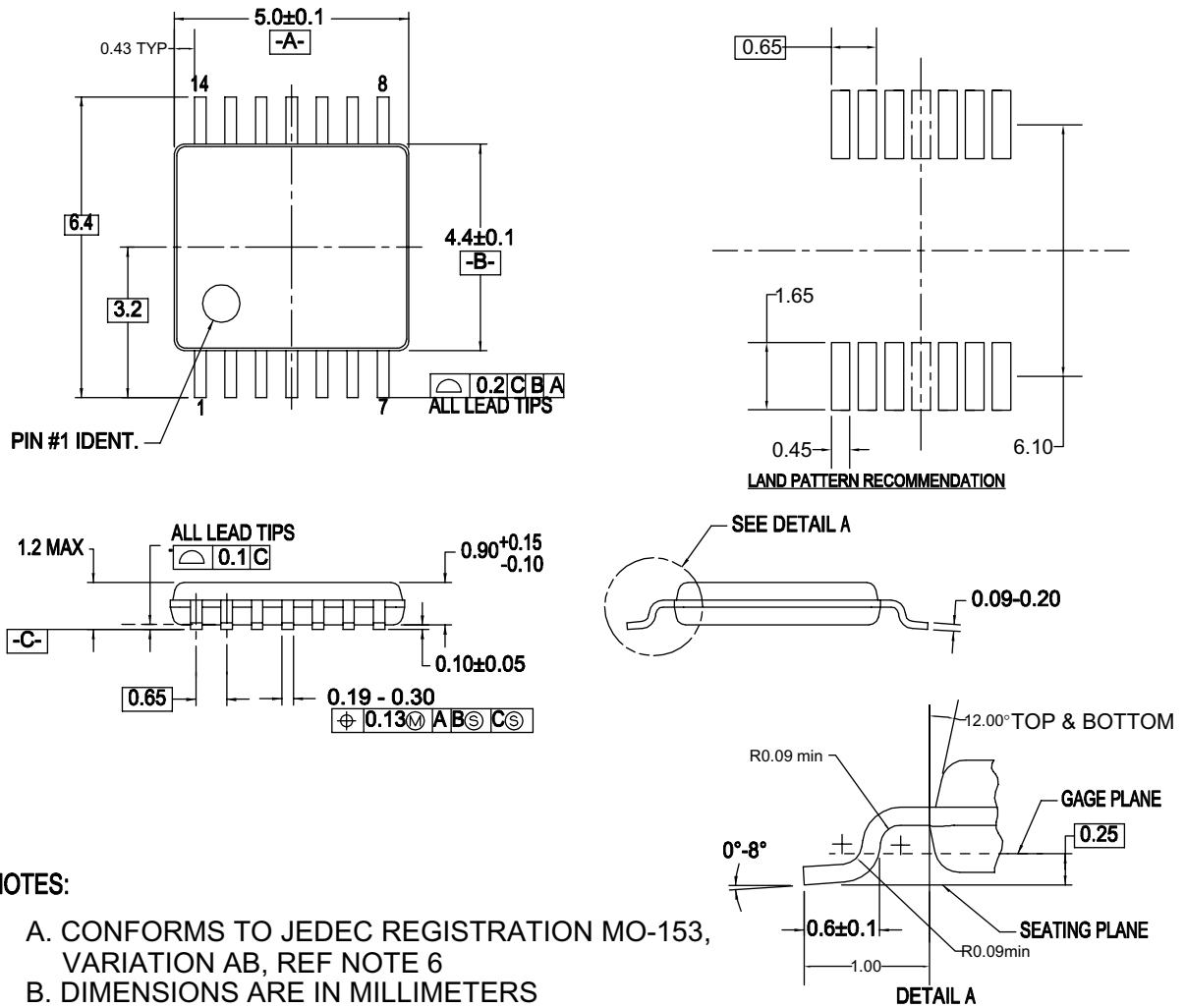
Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

<http://www.fairchildsemi.com/packaging/>

Physical Dimensions (Continued)



NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6
- B. DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

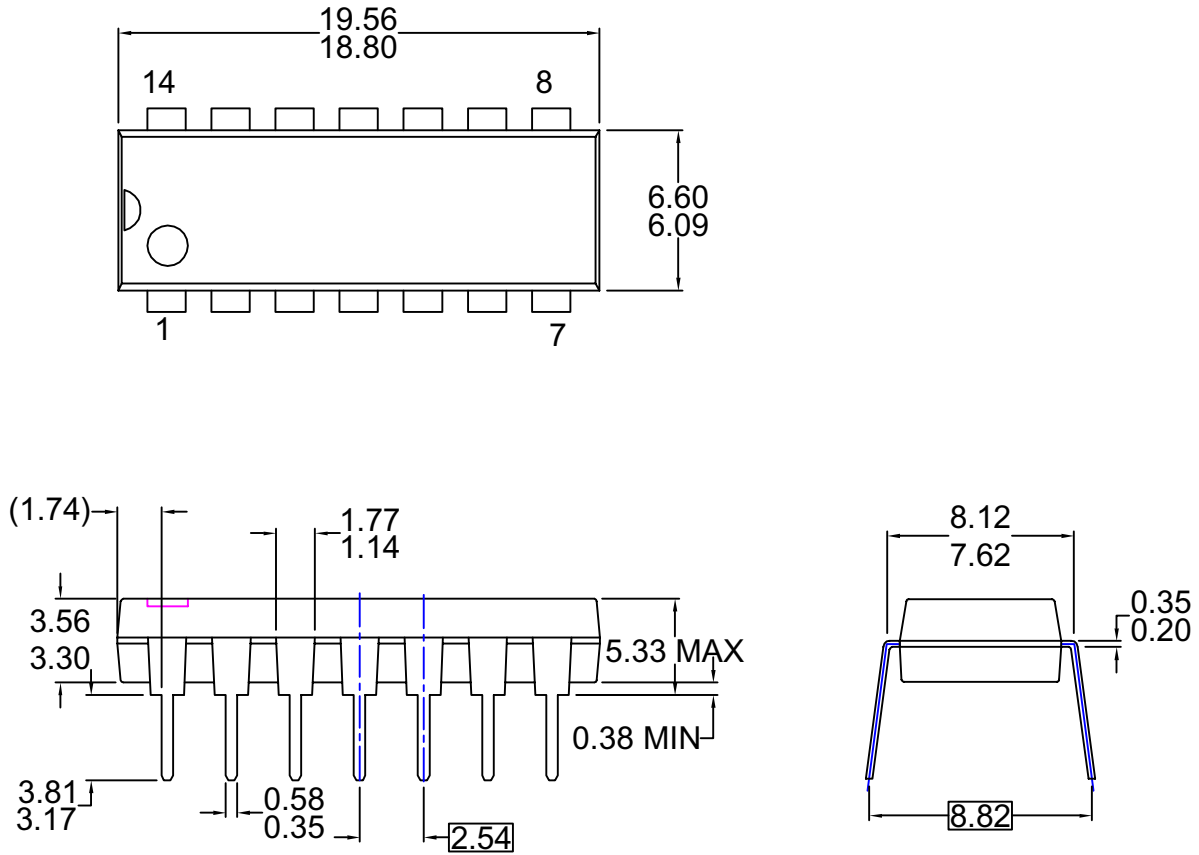
Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

<http://www.fairchildsemi.com/packaging/>

Physical Dimensions (Continued)



- NOTES: UNLESS OTHERWISE SPECIFIED**
THIS PACKAGE CONFORMS TO
A) JEDEC MS-001 VARIATION BA
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS ARE EXCLUSIVE OF BURRS,
MOLD FLASH, AND TIE BAR EXTRUSIONS.
D) DIMENSIONS AND TOLERANCES PER
ASME Y14.5-1994
E) DRAWING FILE NAME: MKT-N14AREV7

Figure 4. 14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.



Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

<http://www.fairchildsemi.com/packaging/>



TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

ACEx®	FPST™	PDP-SPM™	SyncFET™
Build it Now™	FRFET®	Power220®	SYSTEM GENERAL®
CorePLUS™	Global Power Resource™	Power247®	The Power Franchise®
CROSSVOLT™	Green FPS™	POWEREDGE®	the power®
CTL™	Green FPS™ e-Series™	Power-SPM™	franchise
Current Transfer Logic™	GTO™	PowerTrench®	TinyBoost™
EcoSPARK®	i-Lo™	Programmable Active Droop™	TinyBuck™
EZSWITCH™ *	IntelliMAX™	QFET®	TinyLogic®
 ™	ISOPLANAR™	QST™	TINYOPTO™
 ™	MegaBuck™	QT Optoelectronics™	TinyPower™
Fairchild®	MICROCOUPLER™	Quiet Series™	TinyPWM™
Fairchild Semiconductor®	MicroFET™	RapidConfigure™	TinyWire™
FACT Quiet Series™	MicroPak™	SMART START™	µSerDes™
FACT®	MillerDrive™	SPM®	UHC®
FAST®	Motion-SPM™	STEALTH™	Ultra FRFET™
FastvCore™ *	OPTOLOGIC®	SuperFET™	UniFET™
FlashWriter® *	OPTOPLANAR®	SuperSOT™-3	VCX™
		SuperSOT™-6	
		SuperSOT™-8	

* EZSWITCH™ and FlashWriter® are trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild Semiconductor. The datasheet is printed for reference information only.

Rev. I32